Datacon and Ablestik to Share Lab Sites

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RADFELD, AUSTRIA and **RANCHO DOMINGUEZ, CA** — **Datacon**, a supplier of advanced packaging equipment, and

Ablestik

, a supplier of adhesives and specialty materials for semiconductor packaging and microassembly applications, have entered a joint technology development and product evaluation agreement.

The partnership aims to strengthen the respective companies' processes for thin die, stacked die handling and other advanced epoxy processes.

Demo and laboratory sites in Trevose, PA; Radfeld, Austria; Rancho Dominguez, CA; and Shanghai will be open to both companies and their customers.